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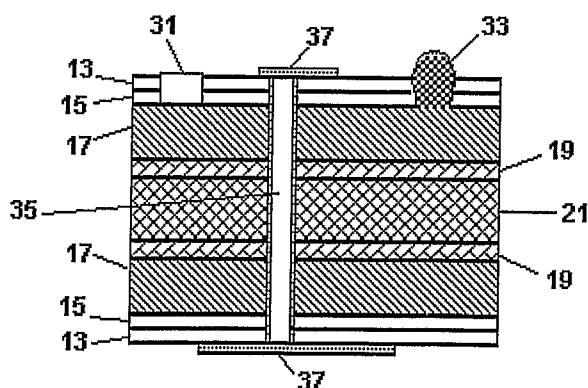
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(54) Title: DEVICE CARRYING AN INTEGRATED CIRCUIT/COMPONENTS AND METHOD OF PRODUCING THE SAME



(57) Abstract: A method of forming an integrated circuit component on an insulating substrate (21), comprising providing a first layer arrangement and a second layer arrangement, each layer arrangement comprising a supply substrate and a dielectric layer (17), the dielectric layer of at least one of the layer arrangements comprising the integrated circuit component therein; attaching the first layer arrangement on one surface of the insulating substrate with the dielectric layer of the first layer arrangement facing the insulating substrate, and attaching the second layer arrangement on an opposing surface of the insulating substrate with the dielectric layer of the second layer arrangement facing the insulating substrate, wherein the first layer arrangement and the second layer arrangement are so arranged to sandwich at least a portion of the insulating substrate between the first and second layer arrangements.

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